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June 2014

FDMC510P

P-Channel PowerTrench[®] MOSFET -20 V, -18 A, 8.0 m Ω

Features

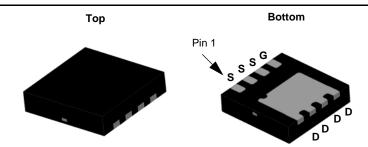
- Max $r_{DS(on)}$ = 8.0 m Ω at V_{GS} = -4.5 V, I_D = -12 A
- Max $r_{DS(on)} = 9.8 \text{ m}\Omega$ at $V_{GS} = -2.5 \text{ V}$, $I_D = -10 \text{ A}$
- Max $r_{DS(on)} = 13 \text{ m}\Omega$ at $V_{GS} = -1.8 \text{ V}$, $I_D = -9.3 \text{ A}$
- Max $r_{DS(on)} = 17 \text{ m}\Omega$ at $V_{GS} = -1.5 \text{ V}$, $I_D = -8.3 \text{ A}$
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- 100% UIL Tested
- Termination is Lead-free and RoHS Compliant
- HBM ESD capability level >2 KV typical (Note 4)

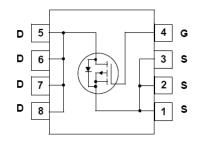
General Description

This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(ON)}$, switching performance and ruggedness.

Applications

- Battery Management
- Load Switch





MLP 3.3x3.3

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V _{DS}	Drain to Source Voltage			-20	V
V_{GS}	Gate to Source Voltage			±8	V
I _D	Drain Current -Continuous	T _C = 25 °C		-18	
	-Continuous	T _A = 25 °C	(Note 1a)	-12	Α
	-Pulsed			-50	
E _{AS}	Single Pulse Avalanche Energy			37	mJ
P _D	Power Dissipation	T _C = 25 °C		41	W
	Power Dissipation	T _A = 25 °C	(Note 1a)	2.3	VV
T _J , T _{STG}	Operating and Storage Junction Temper	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1	a) 53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC510P	FDMC510P	MLP 3.3X3.3	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25 °C		-12		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -16 V, V _{GS} = 0 V			-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.4	-0.5	-1.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = -250 μA, referenced to 25 °C		3		mV/°C
	Static Drain to Source On Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -12 \text{ A}$		6.4	8.0	
r _{DS(on)}		$V_{GS} = -2.5 \text{ V}, I_D = -10 \text{ A}$		7.6	9.8	
		$V_{GS} = -1.8 \text{ V}, I_D = -9.3 \text{ A}$		9.2	13	mΩ
		$V_{GS} = -1.5 \text{ V}, I_D = -8.3 \text{ A}$		11	17	
		$V_{GS} = -4.5 \text{ V}, I_D = -12 \text{ A}, T_J = 125 \text{ °C}$		8.5	12	
g _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, I_{D} = -12 \text{ A}$		75		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 40 V V 0 V	5910	7860	pF
C _{oss}	Output Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	840	1120	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	738	1110	pF

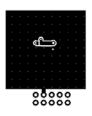
Switching Characteristics

t _{d(on)}	Turn-On Delay Time				15	27	ns
t _r	Rise Time		$V_{DD} = -10 \text{ V}, I_{D} = -12 \text{ A},$		34	55	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -4.5 V, R _{GEN} :	= 6 Ω		338	540	ns
t _f	Fall Time		1		170	272	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } -4.5 \text{ V}$			83	116	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } -2.5 \text{ V}$	$V_{DD} = -10 \text{ V},$		50	70	nC
Q_{gs}	Gate to Source Charge		I _D = -12 A		6.3		nC
Q_{gd}	Gate to Drain "Miller" Charge				20.4		nC

Drain-Source Diode Characteristics

V_{SD}	1Source to Drain Dioge Forward voltage	V _{GS} = 0 V, I _S = -12 A	(Note 2)	-0.70	-1.3	\/
		$V_{GS} = 0 \text{ V}, I_{S} = -2 \text{ A}$	(Note 2)	-0.53	-1.2	v
t _{rr}	Reverse Recovery Time	-I _F = -12 A, di/dt = 100 A/μs		35	57	ns
Q _{rr}	Reverse Recovery Charge			20	32	nC

^{1.} R_{0,JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,JC} is guaranteed by design while R_{0,JA} is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper

- 2: Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0%. 3: Starting T $_J$ = 25°C; P-Ch: L = 3 mH, I $_{AS}$ = -5 A, V $_{DD}$ = -20 V, V $_{GS}$ = -4.5 V. 4: No gate overvoltage rating is implied.

Typical Characteristics T_J = 25 °C unless otherwise noted

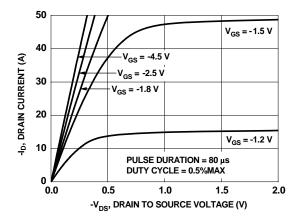


Figure 1. On Region Characteristics

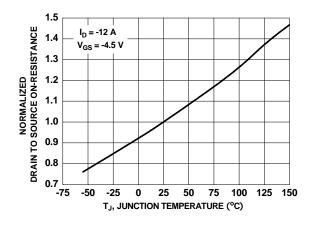


Figure 3. Normalized On Resistance vs. Junction Temperature

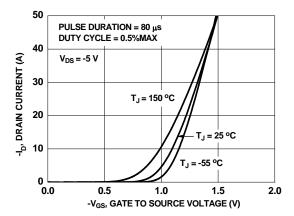


Figure 5. Transfer Characteristics

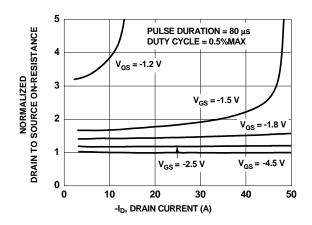


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

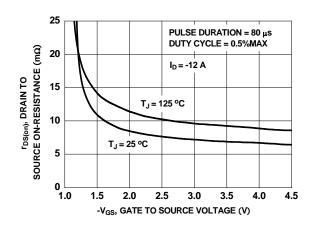


Figure 4. On-Resistance vs. Gate to Source Voltage

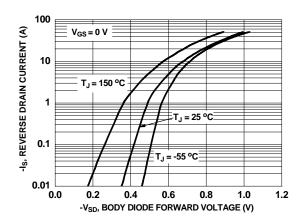


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

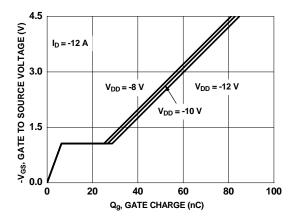


Figure 7. Gate Charge Characteristics

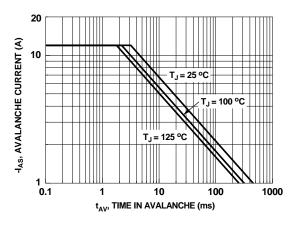


Figure 9. Unclamped Inductive Switching Capability

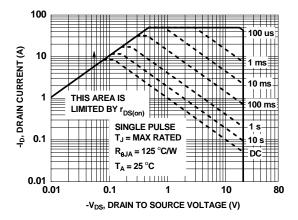


Figure 11. Forward Bias Safe Operating Area

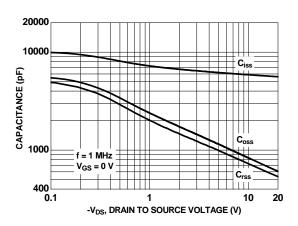


Figure 8. Capacitance vs. Drain to Source Voltage

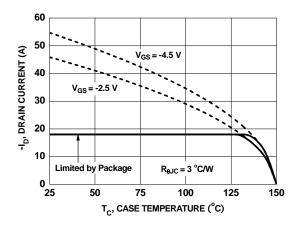


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

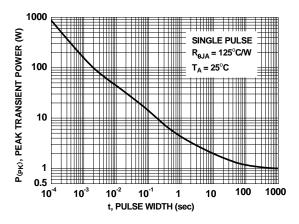


Figure 12. Single Pulse Maximum Power Dissipation



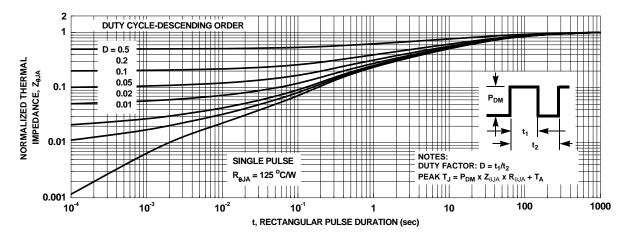
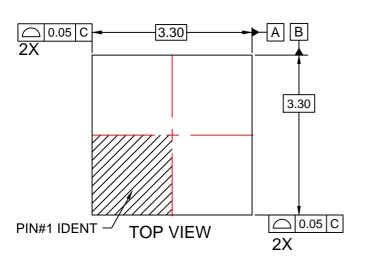
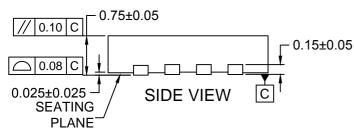
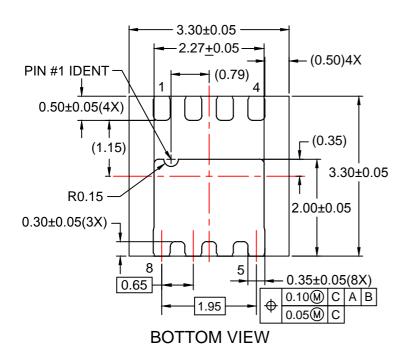
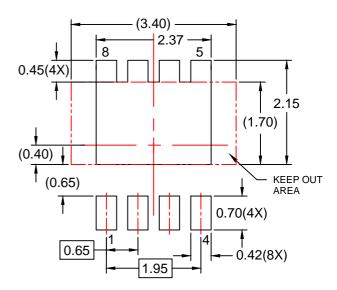


Figure 13. Junction-to-Ambient Transient Thermal Response Curve









RECOMMENDED LAND PATTERN

NOTES:

- A. DOES NOT CONFORM TO JEDEC REGISTRATION MO-229
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. DRAWING FILENAME: MKT-MLP08Srev3.



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